19th Conference on Electrical Performance of Electronic Packaging and Systems

EPEPS 2010

October 24-27, 2010
Austin, Texas
Sponsors
The IEEE Components, Packaging and Manufacturing Technology Society
IEEE Microwave Theory and Techniques Society

Call for Papers

The **general subject of the meeting** is the electrical modeling, design, analysis, and characterization of electronic interconnections and packaging structures. The goal of the meeting is to be the leading conference dealing with advanced and emerging issues in electrical design of interconnect structures and assurance of Signal Integrity. Authors are invited to submit papers describing new technical contributions in the areas broadly covered below:

- Current and future issues related to system level and on-chip interconnections
- Design of high speed links, including jitter and noise management
- Circuit design techniques for high-speed links
- Electrical design, modeling and analysis techniques applicable to ensuring the Signal Integrity of interconnect structures
- Electrical design, modeling and analysis techniques applicable to ensuring the integrity of power and ground delivery at the system and chip levels
- New and innovative interconnect packaging structures and their electrical performance
- Measurement and data analysis techniques for system level and on-chip structures
- Signal integrity in mixed signal and RF integrated circuits and modules
- Electromagnetic modeling and simulation tools and flows
- Advances in transmission-line techniques
- Macromodeling and model reduction as it applies to electrical analysis
- RF/microwave packaging structures and their electrical performance

Conference Co-chairs: Dale Becker, IBM
Conference Web Page: Detailed information can be found at http://www.epeps.org
Paper Submission: Information for authors can be found on the conference web page. Electronic submissions of no more than four pages must be received no later than **July 16, 2010.** Papers should be compliant with the general standards of the IEEE, including inclusion of appropriate references.
Short Courses/Workshops: On Sunday, October 24, a workshop entitled "Future Directions in Packaging" may be presented and short courses/tutorials may be offered.

For more information please see the web site at: http://www.epeps.org
or contact: Dale Becker, email: wbecker@us.ibm.com or
Kelly Sutton, email: pasutton@email.arizona.edu